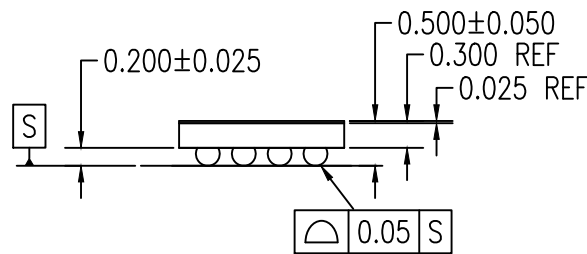
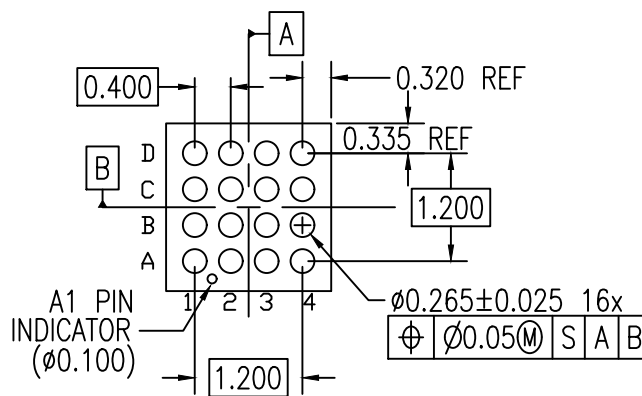


TOP VIEW



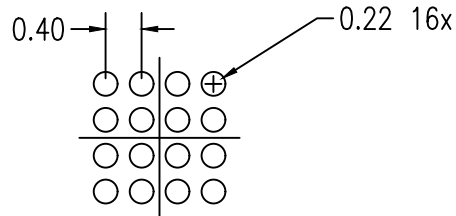
SIDE VIEW



BOTTOM VIEW

NOTES:

1. ALL DIMENSIONS ARE IN MM.
2. PACKAGE BODY SIZE RESULTS FROM 1.87x1.90MM DIE STEP MINUS 30UM KERF.



RECOMMENDED LAND PATTERN DIMENSION

NOTE:

1. ALL DIMENSIONS ARE IN MM, ANGLES IN DEGREES.
2. TOP DOWN VIEW, AS VIEW ON PCB.
3. NSMD LAND PATTERN ASSUMED.
4. LAND PATTERN RECOMMENDATION AS PER IDT DSBGA APPLICATION NOTE.

Package Revision History		
Date Created	Rev No.	Description
Dec.10, 2020	Rev 01	Correct A1 Pin Indicator Location in Bottom View.
Oct.21, 2020	Rev 00	Initial Release